

PROCESS METHOD FOR LASER REMOVAL OF SUBSTRATE
SOLDER MASK

ABSTRACT OF THE DISCLOSURE

A process method for laser removal of substrate solder
5 mask by: providing a substrate with solder pads; covering the
substrate and the solder pads with a solder mask, where the part
of the solder mask facing the substrate is the shielding part and
the part of the solder mask facing the solder pads is the clearing
part; using a camera module to read the QR-code for plate
10 production part number on the substrate; automatically
importing the CAD/CAM data to the laser device, where the
CAD/CAM data corresponds to the plate production part number;
sequentially stripping the cleaning part through the laser beam
according to the CAD/CAM data to make the solder mask form a
15 hollow portion; taking a picture of the substrate and taking out
the processed substrate picture; completing the substrate
processing job if the processed substrate picture and the
CAD/CAM data are the same.

20 FIGURE 1.